IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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| Appl. No. | : | 10/627,479 |
| Applicant | : | Kazushi Higashi et al. |
| Filed | : | July 25, 2003 |
| Title | : | ELECTRONIC PART MOUNTING APPARATUS AND METHOD |
| Conf. No. | : | 4217 |
| TC/A.U. | : | 2835 |
| Examiner | : | TBD |
| Customer No. | : | 000,116 |
| Docket No. | : | 35955 |

INFORMATION DISCLOSURE STATEMENT

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

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In accordance with Rule 56, applicants are aware of the publications listed in the enclosed copy of Patent Office Form 1449. A copy of each of the publications is enclosed herewith. Translations and partial translations enclosed herewith were not prepared by, nor at the direction of, applicants or their assignees. Applicants and Assignees make no representation that these translations are complete or correct.

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Michael W. Garvey
Name of Attorney for Applicant(s)

February 2, 2005
Date

Signature of Attorney

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Respectfully submitted,

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Date: February 2, 2005

| Form PTO-1449 U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE | ATTY. DOCKET NO. **35955** | SERIAL NO. **10/627,479** |
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| INFORMATION DISCLOSURE CITATION BY APPLICANT *(USE SEVERAL SHEETS IF NECESSARY)* | APPLICANT: **Kazushi Higashi et al.** | |
| **Page 1 of 1** | FILING DATE: **July 25, 2003** | GROUP ART UNIT: **4217** |

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| Examiner Initial | | Document No. | Date | Name | Class | Subclass | Filing Date |
|---|---|---|---|---|---|---|---|
| | A | | | | | | |
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| | C | | | | | | |
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| | M | "Ultrasonic Flip Chip Bonding Technology for LSI Chip with High Pin Counts" by Kajiwara et al., from Proceedings of the 7th Symposium on Microjoining and Assembly Technology in Electronics, February 1, 2001, pp. 16166, Japan Welding Society, Tokyo, Japan. |
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| Examiner: | Date Considered |
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